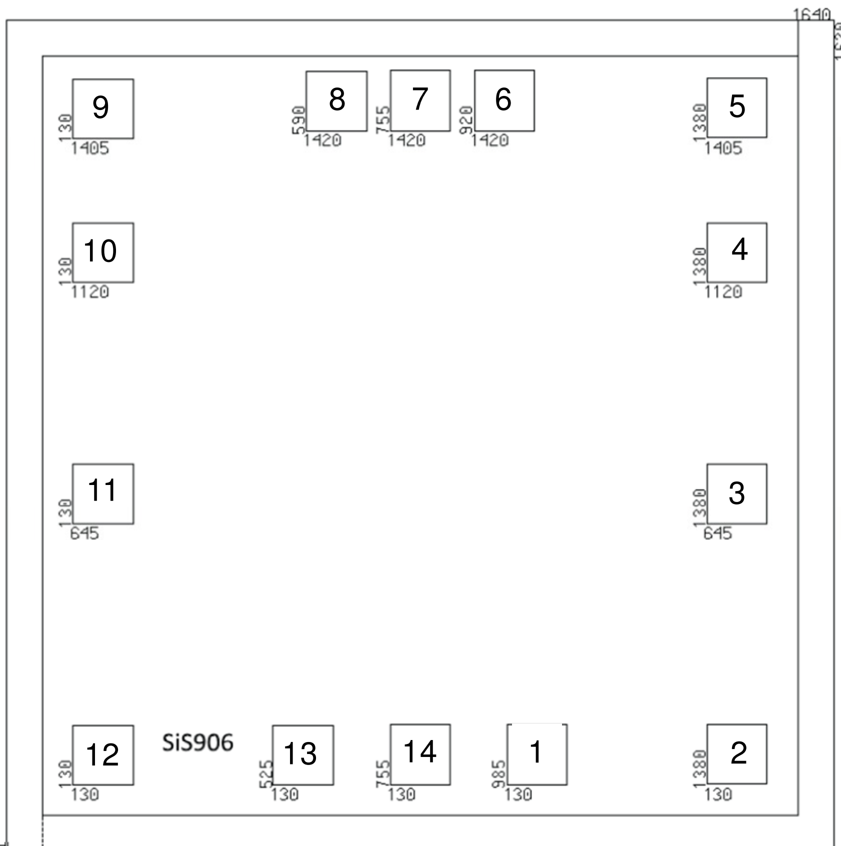
PAD LAYOUT



Pad No.	Function	X	y
1	Out1	985	130
2	In1	1380	130
3	Out2	1380	645
4	In2	1380	1120
5	Out3	1380	1405
6	In3	920	1420
7	GND	755	1420
8	In4	590	1420
9	Out4	130	1405
10	In5	130	1120
11	Out5	130	645
12	In6	130	130
13	Out6	525	130
14	Vcc	755	130

Origin is bottom left corner

CONTACT US FOR THIS CHIP ASSEMBLED IN SOIC OR PDIP PACKAGES & FULL DATASHEET

NOTE:

- This data is supplied for general information only and is believed to be correct at the time of publication.
- For critical applications, the customer is advised to verify device revision and pad coordinates, prior to processing
- Changes can be made without notification from the manufacturer. Silicon Supplies Ltd cannot accept liability in that event

DEVICE	MM74C906	DIE SIZE (MILS)	64.56 X 64.17
MANUFACTURER	SILICON SUPPLIES	BOND PADS MIN (MILS)	4 X 4
APPROVED BY	GEW	TOP METAL	Al
DATE	24/04/19	BACK METAL	Si
SERIAL NUMBER	00571	BACK POTENTIAL	ISOLATED

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